

Dual Row Qfn Package Assembly And Pcb Layout Guidelines

*Covers design, packaging, construction, assembly, and application of all three approaches to Area Array Packaging: Ball Grid Array (BGA), Chip Scale Package (CSP), and Flip Chip (FC) *Details the pros and cons of each technology with varying applications *Examines packaging ramifications of high density interconnects (HDI) This volume provides a comprehensive reference for graduate students and professionals in both academia and industry on the fundamentals, processing details, and applications of 3D microelectronic packaging, an industry trend for future microelectronic packages. Chapters written by experts cover the most recent research results and industry progress in the following areas: TSV, die processing, micro bumps, direct bonding, thermal compression bonding, advanced materials, heat dissipation, thermal management, thermal mechanical modeling, quality, reliability, fault isolation, and failure analysis of 3D microelectronic packages. Numerous images, tables, and didactic schematics are included throughout. This essential volume equips readers with an in-depth understanding of all aspects of 3D packaging, including packaging architecture, processing, thermal mechanical and moisture related reliability concerns, common failures, developing areas, and future challenges, providing insights into key areas for future research and development.

Discover How to Design, Build, and Optimize Customized Mixed-Signal Integrated Circuits for a Wide Variety of Uses Both inspirational and practical, ASIC Design in the Silicon Sandbox offers electronics engineers a hands-on guide to mixed-signal circuits and layouts. The book provides a detailed roadmap for designing and building custom circuits that are optimized for target devices, providing enhanced functionality and lowered cost in finished products. Written by circuit design expert Keith Elliott Barr, this complete resource covers everything from design and optimization methods to standard cell layouts to packaging and testing. Readers will find easy-to-apply information on peripheral circuits; specialty logic structures and memory; logic, binary mathematics, and processing; converters and switched-capacitor techniques; and much more. Filled with hundreds of helpful illustrations, ASIC Design in the Silicon Sandbox features: A wealth of full-color standard cell layouts Multiple approaches to amplifier, oscillator, bandgap, and other analog functions Down-to-earth information on integrated circuit fabrication costs Real-world advice on designing and optimizing custom integrated circuits Practical examples of how to think through new design concepts Step-by-step guidance on entering the fabless semiconductor industry Inside This Cutting-Edge IC Design Reference • The Sandbox • Fabs and Processes • Economics • Design Tools • Standard Cell Design • Peripheral Circuits • Specialty Logic Structures and Memory • Logic, Binary Mathematics, and Processing • Analog Circuits: Amplifiers • The Bandgap Reference • Oscillators, Phase Locked Loops, and RF • Converts and Switched-Capacitor Techniques • Packaging and Testing • Odds and Ends

A comprehensive guide to antenna design, manufacturing processes, antenna integration, and packaging Antenna-in-Package Technology and Applications contains an introduction to the history of AiP technology. It explores antennas and packages, thermal analysis and design, as well as measurement setups and methods for AiP technology. The authors—well-known experts on the topic—explain why microstrip patch antennas are the most popular and describe the myriad constraints of packaging, such as electrical performance, thermo-mechanical reliability, compactness, manufacturability, and cost. The book includes information on how the choice of interconnects is governed by JEDEC for automatic assembly and describes low-temperature co-fired ceramic, high-density interconnects, fan-out wafer level packaging-based AiP, and 3D-printing-based AiP. The book includes a detailed discussion of the surface laminar circuit-based AiP designs for large-scale mm-wave phased arrays for 94-GHz imagers and 28-GHz 5G New Radios. Additionally, the book includes information on 3D AiP for sensor nodes, near-field wireless power transfer, and IoT applications. This important book: • Includes a brief history of antenna-in-package technology • Describes package structures widely used in AiP, such as ball grid array (BGA) and quad flat no-leads (QFN) • Explores the concepts, materials and processes, designs, and verifications with special consideration for excellent electrical, mechanical, and thermal performance Written for students in electrical engineering, professors, researchers, and RF engineers, Antenna-in-Package Technology and Applications offers a guide to material selection for antennas and packages, antenna design with manufacturing processes and packaging constraints, antenna integration, and packaging.

Low Temperature Co-fired Ceramics for System-in-Package Applications at 122 GHz

From Basics to ASICs

Microcontroller Theory and Applications with the PIC18F

3D Microelectronic Packaging

Assembly and Reliability of Lead-Free Solder Joints

This handbook will provide engineers with the principles, applications, and solutions needed to design and manage semiconductor manufacturing operations. Consolidating the many complex fields of semiconductor fundamentals and manufacturing into one volume by deploying a team of world class specialists, it allows the quick look up of specific manufacturing reference data across many subdisciplines.

Design Note Collection, the third book in the Analog Circuit Design series, is a comprehensive volume of applied circuit design solutions, providing elegant and practical design techniques. Design Notes in this volume are focused circuit explanations, easily applied in your own designs. This book includes an extensive power management section, covering switching regulator design, linear regulator design, microprocessor power design, battery management, powering LED lighting, automotive and industrial power design. Other sections span a range of analog design topics, including data conversion, data acquisition, communications interface design, operational amplifier design techniques, filter design, and wireless, RF, communications and network design. Whatever your application -industrial, medical, security, embedded systems, instrumentation, automotive, communications infrastructure, satellite and radar, computers or networking; this book will provide practical design techniques, developed by experts for tackling the challenges of power management, data conversion, signal conditioning and wireless/RF analog circuit design. A rich collection of applied analog circuit design solutions for use in your own designs. Each Design Note is presented in a concise, two-page format, making it easy to read and assimilate.

Contributions from the leading lights in analog design, including Bob Dobkin, Jim Williams, George Erli and Carl Nelson, among others. Extensive sections covering power management, data conversion, signal conditioning, and wireless/RF.

Moisture Sensitivity of Plastic Packages of IC Devices provides information on the state-of-the-art techniques and methodologies related to moisture issues in plastic packages. The most updated, in-depth and systematic technical and theoretical approaches are addressed in the book. Numerous industrial applications are provided, along with the results of the most recent research and development efforts, including, but not limited to: thorough exploration of moisture's effects based on lectures and tutorials by the authors, consistent focus on soft-on-based approaches and methodologies for improved reliability in plastic packages, emerging theories and cutting-edge industrial applications presented by the leading professionals in the field. Moisture plays a key role in the reliability of plastic packages of IC devices, and moisture-induced failures have become an increasing concern with the development of advanced IC devices. This second volume in the Micro- and Opto-Electronic Materials, Structures, and Systems series is a must-read for researchers and engineers alike.

Driven by the fast-growing market for personal electronic devices, integrated circuit complexity has increased as feature sizes shrink. The resulting integrated circuit devices are prone to more frequent failures, which must be found, identified, and fixed. This unique reference uses graphic illustrations to clearly identify all major failure mode types, allowing engineers to spot failures before they occur.

Analog and Power Semiconductor Applications

Design, Assembly Process, Reliability and Modeling

From Fundamentals to Applications

Electronic Packaging and Interconnection Handbook 4/E

Encyclopedia of Packaging Materials, Processes, and Mechanics: Set 1 - Interconnect and Wafer Bonding TechnologyWorld ScientificPower Electronic PackagingDesign, Assembly Process, Reliability and ModelingSpringer Science & Business Media

This open access book contains a structured collection of the complete solutions of all essential axisymmetric contact problems. Based on a systematic distinction regarding the type of contact, the regime of friction and the contact geometry, a multitude of technically relevant contact problems from mechanical engineering, the automotive industry and medical engineering are discussed. In addition to contact problems between isotropic elastic and viscoelastic media, contact problems between transversal-isotropic elastic materials and functionally graded materials are addressed, too. The optimization of the latter is a focus of current research especially in the fields of actuator technology and biomechanics. The book takes into account adhesive effects which allow access to contact-mechanical questions about micro- and nano-electromechanical systems. Solutions of the contact problems include both the relationships between the macroscopic force, displacement and contact length, as well as the stress and displacement fields at the surface and, if appropriate, within the half-space medium. Solutions are always obtained with the simplest available method - usually with the method of dimensionality reduction (MDR) or approaches which use the solution of the non-adhesive normal contact problem to solve the respective contact problem.

This book is written by leading experts with both profound knowledge and rich practical experience in advanced mechanics and the microelectronics industry essential for current and future development. It aims to provide the cutting edge knowledge and solutions for various mechanical related problems, in a systematic way. It contains important and detailed information about the state-of-the-art theories, methodologies, the way of working and real case studies.

Discover How to Launch and Succeed as a Fabless Semiconductor Firm Fabless Semiconductor Implementation takes you step-by-step through the challenges faced by fabless firms in the development of integrated circuits. This expert guide examines the potential pitfalls of IC implementation in the rapidly growing fabless segment of the semiconductor industry and elaborates how to overcome these difficulties. It provides a comprehensive overview of the issues that executives and technical professionals encounter at fabless companies. Filled with over 150 on-target illustrations, this business-building tool presents a clear picture of the entire lifecycle of a fabless enterprise, describing how to envision and execute fabless IC implementation. Inside This Comprehensive Guide to Fabless IC Design - Define and specify the product Understand the customer requirements, the value chain, and the supply chain Select the right implementation approach, including "make" vs. "buy" Choose the best technologies and supply chain Implement IC design, fabrication, and manufacturing Build the operations infrastructure to meet cost and quality requirements Program-manage the distributed supply chain

Failure-Free Integrated Circuit Packages

Mechanics of Microelectronics

Complete PCB Design Using OrCad Capture and Layout

Nanometer CMOS ICs

Semiconductor Manufacturing Handbook, Second Edition

Power Electronic Packaging presents an in-depth overview of power electronic packaging design, assembly, reliability and modeling. Since there is a drastic difference between IC fabrication and power electronic packaging, the book systematically introduces typical power electronic packaging design, assembly, reliability and failure analysis and material selection so readers can clearly understand each task's unique characteristics. *Power electronic packaging is one of the fastest growing segments in the power electronic industry, due to the rapid growth of power integrated circuit (IC) fabrication, especially for applications like portable, consumer, home, computing and automotive electronics. This book also covers how advances in both semiconductor content and power advanced package design have helped cause advances in power device capability in recent years. The author extrapolates the most recent trends in the book's areas of focus to highlight where further improvement in materials and techniques can drive continued advancements, particularly in thermal management, usability, efficiency, reliability and overall cost of power semiconductor solutions.*

The NORTHSUN 90 conference provided a forum for scientists from high latitude countries to discuss their experience of solar energy. The book is divided into two parts, Part One deals with energy conservation and management in buildings and solar and low energy architecture. Part Two covers all aspects of renewable energy; materials science and photovoltaic conversion, weather data, heating and cooling of buildings, hot water systems, wave energy, geothermal energy, energy storage, country programmes and other related topics. In northern latitudes energy savings in buildings of up to 50% can be achieved. NORTHSUN 90 encouraged the attainment of this goal, promoting the use of solar energy in heating and collective work on solar projects of direct benefit to the region.

Thoroughly Revised, State-of-the-Art Semiconductor Design, Manufacturing, and Operations Information Written by 70 international experts and reviewed by a seasoned technical advisory board, this fully updated resource clearly explains the cutting-edge processes used in the design and fabrication of IC chips, on MEMS, sensors, and other electronic devices. *Semiconductor Manufacturing Handbook, Second Edition*, covers the emerging technologies that enable the Internet of Things, the Industrial Internet of Things, data analytics, artificial intelligence, augmented reality, and end smart manufacturing. You will get complete details on semiconductor fundamentals, front- and back-end processes, nanotechnology, photovoltaics, gases and chemicals, fab yield, and operations and facilities. *Nanotechnology and microsystems manufacturing •FinFET and nanoscale silicide formation •Physical design for high-performance, low-power 3D circuits •Epitaxi, anneals, RTP, and oxidation •Microolithography, etching, and ion implantations •Physical, chemical, electrochemical, and atomic layer vapor deposition •Chemical mechanical planarization •Atomic force metrology •Packaging, bonding, and interconnects •Flexible hybrid electronics •Flat-panel,flexible display electronics, and photovoltaic distribution systems •Ultrapure water and filtration •Process chemicals handling and abatement •Chemical and slurry handling systems •Yield management, CIM, and factory automation •Manufacturing execution systems •Advanced process control •Airborne molecular contamination •ESP controls in clean-room environments •Vacuum systems and RF plasma systems •IC manufacturing parts cleaning technology •Vibration and noise design •and much more*

Packaging materials strongly affect the effectiveness of an electronic packaging system regarding reliability, design, and cost. In electronic systems, packaging materials may serve as electrical conductors or insulators, create structure and form, provide thermal paths, and protect the circuits from environmental factors, such as moisture, contamination, hostile chemicals, and radiation. Electronic Packaging Materials and Their Properties examines the array of packaging architecture, outlining the classification of materials and their use for various tasks requiring performance over time. Applications discussed include: interconnections printed circuit boards substrates encapsulants dielectrics die attach materials electrical contacts thermal materials solders *Electronic Packaging Materials and Their Properties* also reviews key electrical, thermal, thermomechanical, mechanical, chemical, and miscellaneous properties as well as their significance in electronic packaging.

ASIC Design in the Silicon Sandbox: A Complete Guide to Building Mixed-Signal Integrated Circuits

Antenna-in-Package Technology and Applications

Moisture Sensitivity of Plastic Packages of IC Devices

Systematic Elimination of Failures

Microcontrollers. Hardware and Firmware for 8-bit and 32-bit devices

Managers, engineers and technicians will use this book during industrial construction of electronics assemblies, while students can use the book to get a grasp of the variety of methods available, together with a discussion of technical concerns. It includes over 200 illustrations, including a photographic guide to defects, and contains many line drawings, tables and flow charts to illustrate the subject of electronics assembly. Soldering in Electronics Assembly looks theoretically at everything needed in a detailed study, but in a practical manner. It examines the soldering processes in the light of electronic assembly type; solder; flux; and cleaning requirements. It has information on every available process. From the most basic hand soldering through to latest innovatory ones such as inert atmosphere wave soldering and zoned forced convection infra-red machines. The book provides a detailed analysis of solder and soldering action; purpose of flux and relevant flux types for any application; classification of assembly variants; assessment and maintenance of solderability. There is also a detailed analysis of soldering process defects and causes. In addition, Soldering in Electronics Assembly contains a new chapter on Ball Grid Array (BGA) technology. A practical guide for the industry covering all the main soldering processes currently in use Cleaning, faults, troubleshooting and standards are all major topics Considers safety and solder process quality assessment

Reviewing the various IC packaging, assembly, and interconnection technologies, this professional reference provides an overview of the materials and the processes, as well as the trends and available options that encompass electronic manufacturing. It covers both the technical issues and touches on some of the reliability concerns with the various technologies applicable to packaging and assembly of the IC. The book discusses the various packaging approaches, assembly options, and essential manufacturing technologies, among other relevant topics.

Advanced Packaging serves the semiconductor packaging, assembly and test industry. Strategically focused on emerging and leading-edge methods for manufacturing and use of advanced packages.

This open access book contains a structured collection of the complete solutions of all essential axisymmetric contact problems. Based on a systematic distinction regarding the type of contact, the regime of friction and the contact geometry, a multitude of technically relevant contact problems from mechanical engineering, the automotive industry and medical engineering are discussed. In addition to contact problems between isotropic elastic and viscoelastic media, contact problems between transversal-isotropic elastic materials and functionally graded materials are addressed, too. The optimization of the latter is a focus of current research especially in the fields of actuator technology and biomechanics. The book takes into account adhesive effects which allow access to contact-mechanical questions about micro- and nano-electromechanical systems. Solutions of the contact problems include both the relationships between the macroscopic force, displacement and contact length, as well as the stress and displacement fields at the surface and, if appropriate, within the half-space medium. Solutions are always obtained with the simplest available method - usually with the method of dimensionality reduction (MDR) or approaches which use the solution of the non-adhesive normal contact problem to solve the respective contact problem.

Materials, Processes, Equipment, and Reliability Area Array Packaging Handbook Fabless Semiconductor Implementation Lead-Free Solder Interconnect Reliability Wafer-Level Chip-Scale Packaging Significant progress has been made in advanced packaging in recent years. Several new packaging techniques have been developed and new packaging materials have been introduced. This book provides a comprehensive overview of the recent developments in this industry, particularly in the areas of microelectronics, optoelectronics, digital health, and bio-medical applications. The book discusses established techniques, as well as emerging technologies, in order to provide readers with the most up-to-date developments in advanced packaging. This book presents the scientific principles, processing conditions, probable failure mechanisms, and a description of reliability performance and equipment required for implementing high-temperature and lead-free die attach materials. In particular, it addresses the use of solder alloys, silver and copper sintering, and transient liquid-phase sintering. While different solder alloys have been used widely in the microelectronics industry, the implementation of sintering silver and transient liquid-phase sintering remains limited to a handful of companies. Hence, the book devotes many chapters to sintering technologies, while simultaneously providing only a cursory coverage of the more widespread techniques employing solder alloys. Addresses the differences between sintering and soldering (the current die-attach technologies), thereby comprehensively addressing principles, methods, and performance of these high-temperature die-attach materials; Emphasizes the industrial perspective, with chapters written by engineers who have hands-on experience using these technologies; Baker Hughes, Bosch and ON Semiconductor, are represented as well as materials suppliers such as Indium; Simultaneously provides the detailed science underlying these technologies by leading academic researchers in the field.

Whether you're designing an electronic system from scratch or engineering the project from someone else's design, the Handbook gives you the tools you need to get the job done faster, cheaper and more reliably than ever. We guarantee it. From development and design to manufacturing and testing, the Handbook has you covered. It's the one resource to turn to first. Why not put it to the test and see for yourself? *Analog and Power Wafer Level Chip Scale Packaging* presents a state-of-art and in-depth overview in analog and power WL CSP design, material characterization, reliability and modeling. Recent advances in analog and power electronic WL CSP packaging are presented based on the development of analog technology and power device integration. The book covers in detail how advances in semiconductor content, analog and power advanced WL CSP design, assembly, materials and reliability have co-enabled significant advances in fan-in and fan-out with redistributed layer (RDL) of analog and power device capability during recent years. Since the analog and power electronic wafer level packaging is different from regular digital and memory IC package, this book will systematically introduce the typical analog and power electronic wafer level packaging design, assembly process, materials, reliability and failure analysis, and material selection. Along with new analog and power WL CSP development, the role of modeling is a key to assure successful package design. An overview of the analog and power WL CSP modeling and typical thermal, electrical and stress modeling methodologies is also presented in the book.

Semiconductor Packaging

Integrated Circuit Packaging, Assembly and Interconnections

The Achievement of 50% Energy Saving: An Environmental Challenge?

Exact Solutions of Axisymmetric Contact Problems

IPC-7525

A thorough revision that provides a clear understanding of the basic principles of microcontrollers using C programming and PIC18F assembly language This book presents the fundamental concepts of assembly language programming and interfacing techniques associated with typical microcontrollers. As part of the second edition's revisions, PIC18F assembly language and C programming are provided in separate sections so that these topics can be covered independent of each other if desired. This extensively updated edition includes a number of fundamental topics. Characteristics and principles common to typical microcontrollers are emphasized. Interfacing techniques associated with a basic microcontroller such as the PIC18F are demonstrated from chip level via examples using the simplest possible devices, such as switches, LEDs, Seven-Segment displays, and the hexadecimal keyboard. In addition, interfacing the PIC18F with other devices such as LCD displays, ADC, and DAC is also included. Furthermore, topics such as CCP (Capture, Compare, PWM) and Serial I/O using C along with simple examples are also provided. Microcontroller Theory and Applications with the PIC18F, 2nd Edition is a comprehensive and self-contained book that emphasizes characteristics and principles common to typical microcontrollers. In addition, the text. Includes increased coverage of C language programming with the PIC18F I/O and interfacing techniques Provides a more detailed explanation of PIC18F timers, PWM, and Serial I/O using C Illustrates C interfacing techniques through the use of numerous examples, most of which have been implemented successfully in the laboratory This new edition of Microcontroller Theory and Applications with the PIC18F is excellent as a text for undergraduate level students of electrical/computer engineering and computer science.

'Soaring Like Eagles: ASM's High-Tech Journey in Asia is an inspiring tale of the phenomenal accomplishment of this company from the perspective of Patrick Lam, ASM's co-founder and CEO of 30 years. The book first traces its growth in three decade-long periods, along with an insider's look at the development of the semiconductor industry. It then examines ASM's success from several angles: its differentiated strategies, its leadership and culture, its innovative practices, its technologies and products, and its preparations from the future.--BOOK JACKET. Provides a comprehensive introduction to the design and analysis of unmanned aircraft systems with a systems perspective Written for students and engineers who are new to the field of unmanned aerial vehicle design, this book teaches the many UAV design techniques being used today and demonstrates how to apply aeronautical science concepts to their design. Design of Unmanned Aerial Systems covers the design of UAVs in three sections—vehicle design, autopilot design, and ground systems design—in a way that allows readers to fully comprehend the science behind the subject so that they can then demonstrate creativity in the application of these concepts on their own. It teaches students and engineers all about: UAV classifications, design groups, design requirements, mission planning, conceptual design, detail design, and design procedures. It provides them with in-depth knowledge of ground stations, power systems, propulsion systems, automatic flight control systems, guidance systems, navigation systems, and launch and recovery systems. Students will also learn about payloads, manufacturing considerations, design challenges, flight software, microcontroller, and design examples. In addition, the book places major emphasis on the automatic flight control systems and autopilots. Provides design steps and procedures for each major component Presents several fully worked, step-by-step examples at component level Includes numerous UAV figures/images to emphasize the application of the concepts Describes real stories that stress the significance of safety in UAV design Offers various UAV configurations, geometries, and weight data to demonstrate the real-world applications and examples Covers a variety of design techniques/processes such that the designer has freedom and flexibility to satisfy the design requirements in several ways Features many end-of-chapter problems for readers to practice Design of Unmanned Aerial Systems is an excellent text for courses in the design of unmanned aerial vehicles at both the upper division undergraduate and beginning graduate levels.

Complete PCB Design Using OrCad Capture and Layout provides instruction on how to use the OrCAD design suite to design and manufacture printed circuit boards. The book is written for both students and practicing engineers who need a quick tutorial on how to use the software and who need in-depth knowledge of the capabilities and limitations of the software package. There are two goals the book aims to reach: The primary goal is to show the reader how to design a PCB using OrCAD Capture and OrCAD Layout. Capture is used to build the schematic diagram of the circuit, and Layout is used to design the circuit board so that it can be manufactured. The secondary goal is to show the reader how to add PSpice simulation capabilities to the design, and how to develop custom schematic parts, footprints and PSpice models. Often times separate designs are produced for documentation, simulation and board fabrication. This book shows how to perform all three functions from the same schematic design. This approach saves time and money and ensures continuity between the design and the manufactured product. Information is presented in the exact order a circuit and PCB are designed Straightforward, realistic examples present the how and why the designs work, providing a comprehensive toolset for understanding the OrCAD software Introduction to the IPC, JEDEC, and IEEE standards relating to PCB design Full-color interior and extensive illustrations allow readers to learn features of the product in the most realistic manner possible

Soaring Like Eagles - ASM's High-Tech Journey in Asia

Power Electronic Packaging

Manufacturing and Assembly

Gallium Nitride Power Devices

Handbook of Contact Mechanics

While MEMS technology has progressed rapidly, commercialization of MEMS has been hindered by packaging technology barriers and costs. One of the key issues in the industrialization of MEMS, MOEM and ultimately Nanoelectrical devices is the development of appropriate packaging solutions for the protection, assembly, and long term reliable operation. This book rigorously examines the properties of the materials used in MEMS and MOEM assembly then evaluates them in terms of their routing, electrical performance, thermal management and reliability. With this as a starting point, the book moves on to discuss advanced packaging methods such as: molded thermoplastic packages for MEMS, wafer-assembled RFID, and wafer-level stacked packaging. This textbook provides a comprehensive, fully-updated introduction to the essentials of nanometer CMOS integrated circuits. It includes aspects of scaling to even beyond 12nm CMOS technologies and designs. It clearly describes the fundamental CMOS operating principles and presents substantial insight into the various aspects of design implementation and application. Coverage includes all associated disciplines of nanometer CMOS ICs, including physics, lithography, technology, design, memories, VLSI, power consumption, variability, reliability and signal integrity, testing, yield, failure analysis, packaging, scaling trends and road blocks. The text is based upon in-house Philips, NXP Semiconductors, Applied Materials, ASML, IMEC, ST-Ericsson, TSMC, etc., courseware, which, to date, has been completed by more than 4500 engineers working in a large variety of related disciplines: architecture, design, test, fabrication process, packaging, failure analysis and software.

This book focuses on the assembly and reliability of lead-free solder joints. Both the principles and engineering practice are addressed, with more weight placed on the latter. This is achieved by providing in-depth studies on a number of major topics such as solder joints in conventional and advanced packaging components, commonly used lead-free materials, soldering processes, advanced specialty flux designs, characterization of lead-free solder joints, reliability testing and data analyses, design for reliability, and failure analyses for lead-free solder joints. Uniquely, the content not only addresses electronic manufacturing services (EMS) on the second-level interconnects, but also packaging assembly on the first-level interconnects and the semiconductor back-end on the 3D IC integration interconnects. Thus, the book offers an indispensable resource for the complete food chain of electronics products.

GaN is considered the most promising material candidate in next-generation power device applications, owing to its unique material properties, for example, bandgap, high breakdown field, and high electron mobility. Therefore, GaN power device technologies are listed as the top priority to be developed in many countries, including the United States, the European Union, Japan, and China. This book presents a comprehensive overview of GaN power device technologies, for example, material growth, property analysis, device structure design, fabrication process, reliability, failure analysis, and packaging. It provides useful information to both students and researchers in academic and related industries working on GaN power devices. GaN wafer growth technology is from Enkris Semiconductor, currently one of the leading players in commercial GaN wafers. Chapters 3 and 7, on the GaN transistor fabrication process and GaN vertical power devices, are edited by Dr. Zhihong Liu, who has been working on GaN devices for more than ten years. Chapters 2 and 5, on the characteristics of polarization effects and the original demonstration of AlGaIn/GaN heterojunction field-effect transistors, are written by researchers from Southwest Jiaotong University. Chapters 8, 8, and 9, on surface passivation, reliability, and package technologies, are edited by a group of researchers from the Southern University of Science and Technology of China.

Die-Attach Materials for High Temperature Applications in Microelectronics Packaging

MEMS/MOEM Packaging

Soldering in Electronics Assembly

Semiconductor Manufacturing Handbook

In semiconductor manufacturing, understanding how various materials behave and interact is critical to making a reliable and robust semiconductor package. Semiconductor Packaging: Materials Interaction and Reliability provides a fundamental understanding of the underlying physical properties of the materials used in a semiconductor package. By tying together the disparate elements essential to a semiconductor package, the authors show how all the parts fit and work together to provide durable protection for the integrated circuit chip within as well as a means for the chip to communicate with the outside world. The text also covers packaging materials for MEMS, solar technology, and LEDs and explores future trends in semiconductor packages.

Energy Conservation in Buildings

Advanced Packaging

Materials Interaction and Reliability

Analog Circuit Design Volume Three

Electronic Packaging Materials and Their Properties